



Super  
cost  
saver

Model ID  
**PSX307**

Model No. NM-EFP1A

|  |  |
|--|--|
| Model ID                                   | PSX307   |
| Model No.                                  | NM-EFP1A   |
| Cleaning Method                            | Parallel plate RF back-sputtering method   |
| Gas for Electrical Discharge <sup>*1</sup> | Ar [option:O <sub>2</sub> ]  |
| Substrate Dimensions                       | L 50 mm X W 20 mm to L 250 mm X W 75 mm <sup>*2</sup> incl. S type option<br>L 50 mm X W 20 mm to L 330 mm X W 120 mm incl. M type option  |
| Substrate Thickness                        | 0.5 mm to 2.0 mm   |
| Dimensions / Mass <sup>*3</sup>            | W 930 mm X D 1100 mm X H 1 450 mm / 555 kg<br>W 1 764 mm X D 1 100 mm X H 1 450 mm / 850 kg incl. S type option<br>W 1 764 mm X D 1 100 mm X H 1 450 mm / 770 kg incl. M type option |
| Power Source <sup>*4</sup>                 | 1-phase AC 200 V, 2.00 kVA [Full Load 5.00 kVA]  |
| Pneumatic Source                           | 0.49 MPa or more, 6.5 L/min [A.N.R.]   |

\*Please refer to the specifications on details.

\*1: If the optional oxygen gas is selected as a discharge gas, nitrogen gas is also required to dilute exhaust.

\*2: For W 70.1mm to W 75mm, the electrode in the chamber is required separately.

\*3: Tolerance of equipment dimensions is ±5mm, Touch panel and condition lamp is not included. Mass varies depending on configuration.

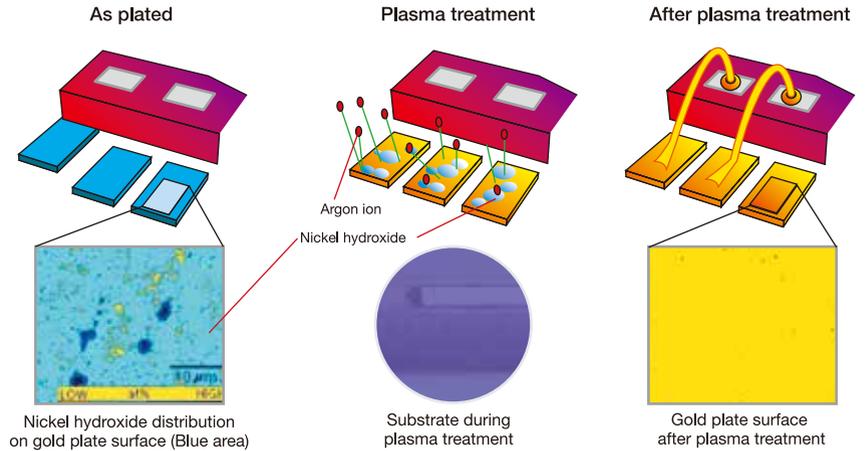
\*4: Compatible with 1-phase 208/220/230/240 V

## The reason why an extra-thin gold plated electrode can be used

When an extra-thin gold plated electrode is used, nickel compounds are formed on a surface after the heat treatment by the die-bonding cure. These nickel compounds impair the wire bonding performance, thus it is said that a thin gold plated electrode is unsuitable for wire bonding. However, the argon plasma treatment eliminates the nickel compounds, therefore stable wire bonding can be performed on an extra-thin and extra-cheap gold plated electrode.

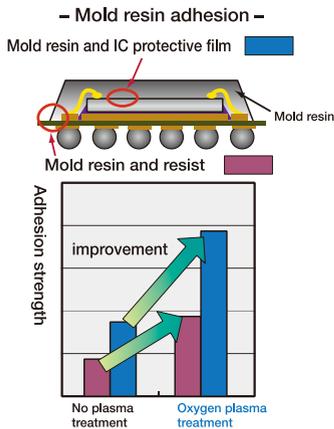
When you use the following patents (process patents or product patents) with non-PFSC products, you are legally bound to sign a contract with Panasonic Co., Ltd.

Japanese patents 2 783 133, 2 783 260, 3 000 877  
U.S.patents 5 647 942, 5 767 008, 6 331 347  
U.K.patents 2 297 981  
German patents 19 606 074



## Surface reforming by oxygen plasma

Surface reforming by oxygen radical improves mold resin adhesion and under-fill wettability. (Option)



## Transfer system options



## Safety Cautions

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

Panasonic Group products are built with the environment in mind.

Please check the homepage for the details.  
[panasonic.com/global/corporate/sustainability](http://panasonic.com/global/corporate/sustainability)

Inquiries...

Panasonic Corporation  
Process Automation Business Division

3-1-1 Inazu-cho, Toyonaka City, Osaka 561-0854, Japan  
TEL +81-6-6866-8630  
FAX +81-6-6862-0422

All data as of January 1, 2020

Ver. January 1, 2020

© Panasonic Corporation 2020